

03/02/01 RECORDATI PA

03-15-2001



101637881

1e attached original document(s)

To the Honorable Assistant Secretary and Commissioner or copy(ies) thereof.

1. Name of conveying party(ies): Mituso ZEN Additional name(s) of conveying party(ies) attached? No

2. Name and address of receiving party(ies): Name: SENJU METAL INDUSTRY CO., LTD. Street Address: 23, Senju Hashido-cho, Adachi-ku, Tokyo, Japan Additional name(s) & address(es) attached? No

3. Nature of conveyance: X Assignment Merger Security Agreement Change of Name Other Execution Date: February 1, 2001

J1017 U.S. PTO 09/796463 03/02/01

4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application is: February 1, 2001 A. Patent Application No.(s) B. Patent No.(s) issued 09296463 Additional numbers attached? No

5. Name and address of party to whom correspondence concerning document should be mailed: Name: WENDEROTH, LIND & PONACK, L.L.P. Attn: Michael S. Huppert, Esq. Street Address: 2033 K Street, N.W., Suite 800 City: Washington, State: DC ZIP: 20006

6. Total number of applications and patents involved: 1 7. Total fee (37 CFR 3.41): \$40.00 X Enclosed (Check No. 43280) Authorized to be charged to deposit account 8. Deposit account number: 23-0975 (Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Michael S. Huppert, Reg. No. 40,268 Name of Person Signing Signature March 2, 2001 Date Total number of pages including cover sheet: 3

OMB No. 0651-0011 (exp. 4/94) 03/08/2001 MWOLDER1 00000069 09796463 02 FC:581 40.00 DP Mail documents to be recorded with required cover sheet information:

Do not detach this portion

THE COMMISSIONER IS AUTHORIZED TO CHARGE ANY DEFICIENCY IN THE FEE FOR THIS PAPER TO DEPOSIT ACCOUNT NO. 23-0975.

Commissioner and Assistant Secretary of Patents and Trademarks Box Assignments Washington, D.C. 20231

Public burden reporting for this sample cover sheet is estimated to average about 30 minutes per document to be recorded, including time for reviewing the document and gathering the data needed, and completing and reviewing the sample cover sheet. Send comments regarding this burden estimate to the U.S. Patent and Trademark Office, Office of Information Systems, PK2-1000C, Washington, D.C. 20231, and the Office of Management and Budget, Paperwork Reduction Project (0651-0011), Washington, D.C. 20503.

ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration paid to each of the undersigned

Mituso ZEN

**Insert Name(s)
of Inventor(s)**

**Insert Name(s)
of Assignee(s)**

Address

**Title of
Invention**

**Date of Signing
of Application**

the undersigned hereby sell(s) and assign(s) to

SENJU METAL INDUSTRY CO., LTD.

of 23, Senju Hashido-cho, Adachi-ku, Tokyo, Japan

(hereinafter designated as the Assignee) the entire right, title and interest for the United States as defined in 35 USC 100, in the invention known as

AUTOMATIC WAVE SOLDERING APPARATUS AND METHOD

for which an application for patent in the United States has been executed by the undersigned on

February 1, 2001

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division or reissue thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

PATENT

REEL: 011580 FRAME: 0009

The undersigned hereby grant(s) the firm of WENDEROTH, LIND & PONACK, L.L.P., 2033 K Street, N.W., Suite 800, Washington, DC 20006, the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date February 1, 2001, Name of Inventor MITSUO ZEN Mitsuo ZEN
Date _____, Name of Inventor _____
Date _____, Name of Inventor _____
Date _____, Name of Inventor _____
Date _____, Name of Inventor _____
Date _____, Name of Inventor _____

(This assignment should preferably be acknowledged before a United States Consul. If not, then the execution by the Inventor(s) should be witnessed by at least two witnesses who sign here.)

Witness Yoshihiro Tsubokawa
Witness Fumihiko Imai

ACKNOWLEDGEMENT

_____ } ss

This _____ day of _____, _____, before me
personally came the above-named _____

to me personally known as the individual(s) who executed the foregoing assignment, who did acknowledge to me that he (they) executed the same of his (their) own free will for the purposes therein set forth.

SEAL _____
Official Signature
_____ Official Title

The above application may be more particularly identified as follows:

U.S. Application Serial No. _____ Filing Date _____
Applicant Reference Number _____ Atty Docket No. _____
Title of Invention _____
